



## Material Content Data Sheet



<b>Sales Product Name</b>	TLS810C1EJ V33			<b>Issued</b>	4. March 2019			
<b>MA#</b>	MA005209784							
<b>Package</b>	PG-DSO-8-52			<b>Weight*</b>	83.69 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.989	1.18	1.18	11815	11815
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8696	
wire	non noble metal	copper	7440-50-8	29.548	35.31	36.23	353077	362317
	non noble metal	copper	7440-50-8	0.057	0.07	0.07	683	683
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1207
plastics	plastics	epoxy resin	-	4.647	5.55		55530	
	inorganic material	silicondioxide	60676-86-0	45.764	54.68	60.35	546853	603590
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8306	8306
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8657	8657
glue	plastics	epoxy resin	-	0.097	0.12		1158	
	noble metal	silver	7440-22-4	0.291	0.35	0.47	3474	4632
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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